

# FLIP CHIP PART NUMBERING SYSTEM

**FC 48**

Flip Chip

FC = Standard Flip Chip  
FCW = Bumped Wafer  
FCQ = Quartz Flip Chip  
FCWQ = Quartz Wafer  
FCN = Bumpless Chip  
FCWN = Bumpless Wafer

Number Bumps

Actual Count

Bump Diameter

**D**

**6.3**

Die Size

In millimeter  
6.3 = 6.3mm SQ  
10 x 15 = 10mm x 15mm

Bump Material

E = Eutectic Sn63  
G = Gold over Nickel  
C = Lead Free Sn/Ag/Cu  
A = Aluminum (Bumpless)

**E**

**457**

Bump Pitch

in  $\mu\text{m}$   
(1000m = 1.0 $\mu\text{m}$ )

**DC**

Daisy Chain

A = 100 x 127 $\mu\text{m}$     H = 105 $\mu\text{m}$  SQ  
B = 115 $\mu\text{m}$  SQ      K = 88 $\mu\text{m}$   
C = 160 $\mu\text{m}$           G = 100-135 $\mu\text{m}$   
D = 190 $\mu\text{m}$           R = 100 $\mu\text{m}$  SQ  
E = 56 $\mu\text{m}$  SQ        T = 50 $\mu\text{m}$  SQ